Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

MBRS240LT3G, NRVBS240LT3G, NRVBS240LN

These devices employ the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Overvoltage Protection
- Low Forward Voltage Drop
- ESD Ratings:
 - Human Body Model = 3B (> 16000 V)
 - Machine Model = C (> 400 V)
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These are Pb-Free Devices

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Maximum Temperature of 260°C/10 Seconds for Soldering
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable



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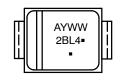
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SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 40 VOLTS



SMB CASE 403A

MARKING DIAGRAM



2BL4	= Specific Device Code
А	= Assembly Location**
Y	= Year
WW	= Work Week
•	= Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS240LT3G	SMB (Pb-Free)	2,500 / Tape & Reel
NRVBS240LT3G*	SMB (Pb-Free)	2,500 / Tape & Reel
NRVBS240LNT3G*	SMB (Pb-Free)	2,500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V _R , $T_C = 100^{\circ}C$)	Ι _Ο	2.0	A
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T_C = 105°C)	I _{FRM}	4.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	25	A
Storage Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature	TJ	–55 to +150	°C
Voltage Rate of Change (Rated V _R , $T_J = 25^{\circ}C$)	dv/dt	10,000	V/µs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JL} \ R_{ heta JA}$	18 78	°C/W

1. Mounted with minimum recommended pad size, PC Board FR4.

2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

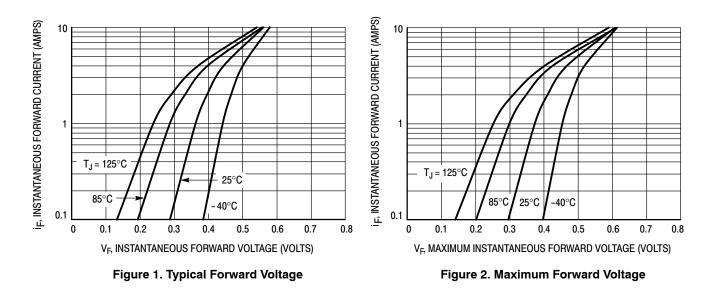
ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Va	lue	Unit
Maximum Instantaneous Forward Voltage (Note 3)	V _F	T _J = 25°C	T _J = 125°C	V
see Figure 2 (I _F = 2.0 A) (I _F = 4.0 A)		0.43 0.54	0.375 0.55	
Maximum Instantaneous Reverse Current (Note 3)	۱ _R	T _J = 25°C	T _J = 100°C	mA
see Figure 4 (V _R = 40 V) (V _R = 20 V)		2.0 0.5	60 40	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 250 µs, Duty Cycle \leq 2.0%.

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TYPICAL CHARACTERISTICS



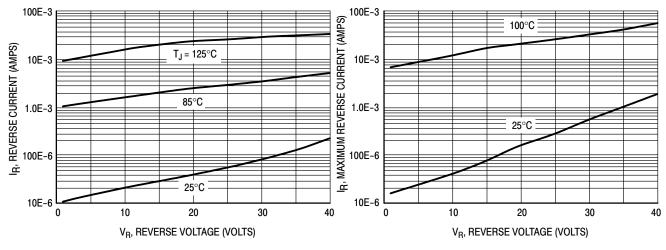
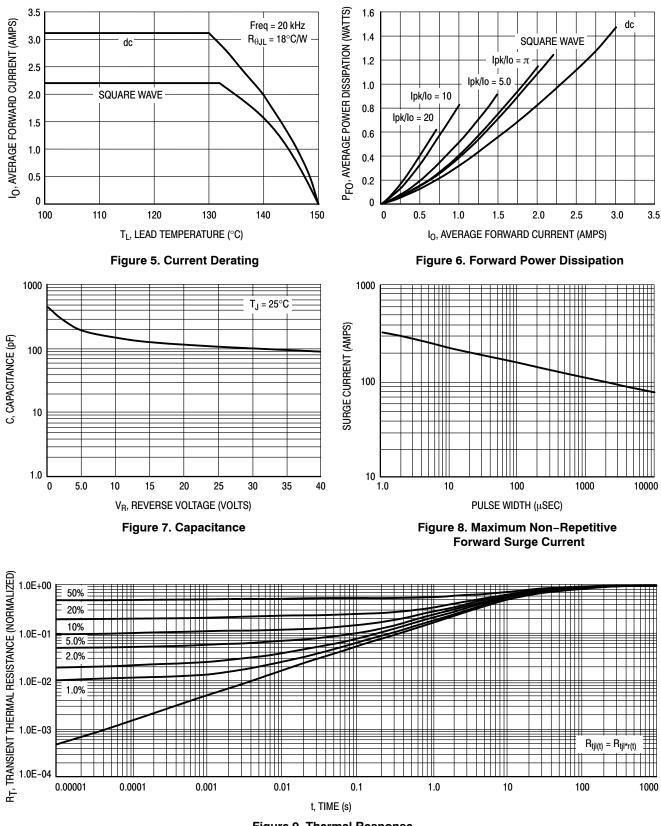


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

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TYPICAL CHARACTERISTICS

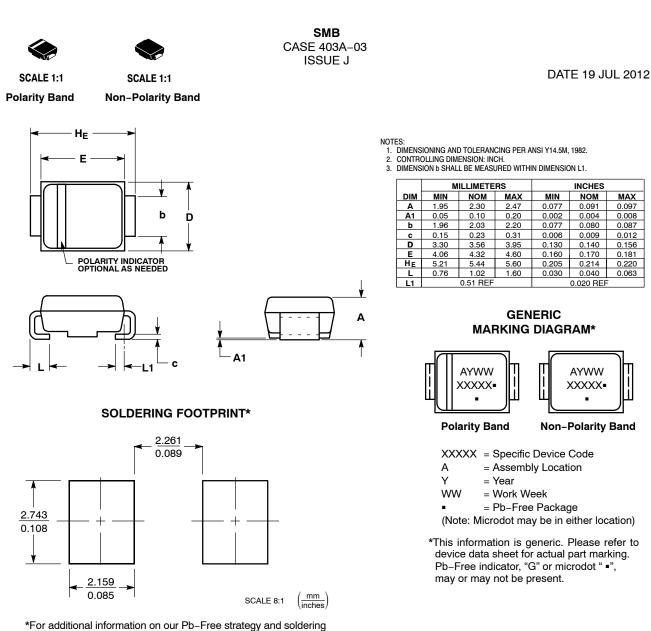




MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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